



LTM4600 104LD 15mm x 15mm x 2.82mm (TABLE OF MATERIAL DECLARATION)

The LTM4600 is RoHS compliant per EU RoHS Directive 2015/863/EU.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE).

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Material Analysis (weight %)
1	Substrate	Circuit Board	0.2124	Barium Compounds	7727-43-7	0.0032	1.50
				Filler Substances (Silica crystalline)	14808-60-7	0.0848	39.91
				Copper metal	7440-50-8	0.1190	56.00
				Copper compounds	1328-53-6	0.0000	0.02
				Ecotoxic substances	7439-92-1	0.0000	0.00
				Gold metal or alloy	7440-57-5	0.0010	0.46
				Nickel	7440-02-0	0.0045	2.10
				Zinc	7440-66-6	0.0000	0.01
2	Solder Paste	Alloy	0.0153	Sn	7440-31-5	0.0145	95.00
				Sb	7440-36-0	0.0008	5.00
3	Passive/Active Components		0.5803	Iron Powder (Fe)	7439-89-6	0.3810	65.66
				Copper (Cu)	7440-50-8	0.1236	21.30
				Nickel (Ni)	7440-02-0	0.0090	1.55
				Tin (Sn)	7440-31-5	0.0055	0.95
				Ceramic (Ba) Compounds	12047-27-7	0.0612	10.55
4	Active ICs	Silicon	0.0099	Silicon	7440-21-3	0.0099	100.00
5	Wire	Gold	0.0025	Au	7440-57-5	0.0025	99.99
6	Encapsulation	Epoxy Resin	0.9064	Fused Silica (60-95)	60676-86-0	0.6998	77.20
				Epoxy resin (2-20)	non-disclosure	0.0807	8.90
				Phenol resin (2-20)	non-disclosure	0.0807	8.90
				Crytalline Silica (<6)	14808-60-7	0.0272	3.00
				Carbon Black (<=1)	1333-86-4	0.0045	0.50
				Metal Hyrdoxide (<=30)	non-disclosure	0.0136	1.50
Total Package weight			1.7268				

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.